Low Voltage 32K x 8 SRAM

Features

☐ ESD protection > 2000 V

(MIL STD 883C M3015.7)

☐ Package: SOP28 (300/330 mil)

☐ Latch-up immunity >100 mA

Description

The AS62V256A-70SIN is a static RAM manufactured using a CMOS pro-cess technology with the following operating modes:

- Read - Standby

- Write - Data Retention

The memory array is based on a 6-Transistor cell.

The circuit is activated by the falling edge of \overline{E} . The address and control inputs open simultaneously. According to the information of \overline{W} and \overline{G} , the data inputs, or outputs, are active. In a Read cycle, the data outputs are activated by the falling edge of \overline{G} , afterwards the data word will be available at the outputs DQ0-DQ7. After the address change, the data outputs

go High-Z until the new information is available. The data outputs have no preferred state. The Read cycle is finished by the falling edge of \overline{W} , or by the rising edge of \overline{E} , respectively.

Data retention is guaranteed down to 2 V. With the exception of \overline{E} , all inputs consist of NOR gates, so that no pull-up/pull-down resistors are required.

Pin Configuration

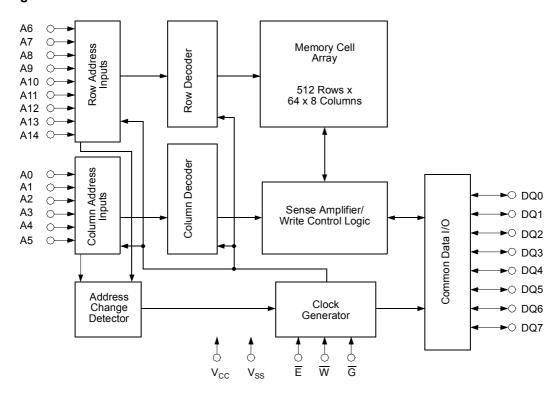
28 VCC A14 $\overline{\mathsf{w}}$ A12 2 27 Α7 3 26 A13 A6 25 Α8 A5 Α9 5 24 23 A4 6 A11 А3 22 G SOP A2 8 21 A10 Α1 9 20 E A0 19 DQ7 10 DQ0 11 18 DQ6 DQ1 12 17 DQ5 DQ2 13 16 DQ4 VSS 15 DQ3

Pin Description

Signal Name	Signal Description
A0 - A14	Address Inputs
DQ0 - DQ7	Data In/Out
Ē	Chip Enable
G	Output Enable
W	Write Enable
VCC	Power Supply Voltage
VSS	Ground

Top View

Block Diagram



Truth Table

Operating Mode	Ē	w	G	DQ0 - DQ7
Standby/not selected	Н	*	*	High-Z
Internal Read	L	Н	Н	High-Z
Read	L	Н	L	Data Outputs Low-Z
Write	L	L	*	Data Inputs High-Z

* H or L



Characteristics

All voltages are referenced to V_{SS} = 0 V (ground).

All characteristics are valid in the power supply voltage range and in the operating temperature range specified. Dynamic measurements are based on a rise and fall time of \leq 5 ns, measured between 10 % and 90 % of V_I , as well as input levels of V_{IL} = 0.2 V and V_{IH} = 2.8 V. The timing reference level of all input and output signals is 1.5 V, with the exception of the t_{dis} -times and t_{en} -times, in which cases transition is measured \pm 200 mV from steady-state voltage.

Absolute Maximum Ratings ^a	Symbol	Min.	Max.	Unit
Power Supply Voltage	V _{CC}	-0.3	4.6	V
Input Voltage	V _I	-0.5	V _{CC} + 0.5 ^b	V
Output Voltage	V _O	-0.5	V _{CC} + 0.5 ^b	V
Power Dissipation	P _D	-	1	W
Operating Temperature	Та	-40	85	°C
Storage Temperature	T _{stg}	-65	150	°C
Output Short-Circuit Current at V_{CC} = 3.3 V and V_{O} = 0 V c	I _{os}		100	mA

^a Stresses greater than those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at condition above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability

^c Not more than 1 output should be shorted at the same time. Duration of the short circuit should not exceed 30 s.

Recommended Operating Conditions	Symbol	Conditions	Min.	Max.	Unit
Power Supply Voltage	V _{CC}		2.5	3.6	V
Input Low Voltage d	V _{IL}		-0.3	0.5	V
Input High Voltage	V _{IH}		2.0	V _{CC} + 0.3	V

d -2 V at Pulse Width 30 ns



b Maximum voltage is 4.6 V

Electrical Characteristics	Symbol	Co	nditions	Min.	Max.	Unit
Supply Current - Operating Mode	I _{CC(OP)}	V _{CC} V _{IL} V _{IH} t _{cW}	= 3.6 V = 0.5 V = 2.0 V = 70 ns = 70 ns		90 70	mA mA
Supply Current - Standby Mode (CMOS level)	I _{CC(SB)}	V _{CC} V _E I-Type	= 3.6 V = $\text{V}_{\text{CC}} - 0.2 \text{ V}$		10	μΑ
Supply Current - Standby Mode (TTL level)	I _{CC(SB)1}	V _{CC} V _E I-Type	= 3.6 V = 2.0 V		10	mA
Output High Voltage	V _{OH}	V _{CC}	= 2.5 V	2.2		V
Output Low Voltage	V _{OL}	I _{OH} V _{CC} I _{OL}	=-1.0 mA = 2.5 V = 2.1 mA		0.4	V
Input High Leakage Current	I _{IH}	V _{CC}	= 3.6 V = 3.6 V		2	μΑ
Input Low Leakage Current	I _{IL}	V _{IH} V _{CC} V _{IL}	= 3.6 V = 3.6 V = 0 V	-2		μΑ
Output High Current	Іон	V _{CC}	= 2.5 V = 2.2 V		-1.0	mA
Output Low Current	I _{OL}	V _{OH} V _{CC} V _{OL}	= 2.5 V = 0.4 V	2.1		mA
Output Leakage Current		.,	0.01/			
High at Three-State Outputs	I _{OHZ}	V _{CC} V _{OH}	= 3.6 V = 3.6 V		2	μA
Low at Three-State Outputs	I _{OLZ}	V _{CC}	= 3.6 V = 0 V	-2		μA



Switching Characteristics	Syn	nbol	7	Unit		
Read Cycle	Alt.	IEC	Min.	Max.	Onn	
Read Cycle Time	t _{RC}	t _{cR}	70		ns	
Address Access Time to Data Valid	t _{AA}	t _{a(A)}		70	ns	
Chip Enable Access Time to Data Valid	t _{ACE}	t _{a(E)}		70	ns	
G LOW to Data Valid	t _{OE}	t _{a(G)}		25	ns	
EHIGH to Output in High-Z	t _{HZCE}	t _{dis(E)}		15	ns	
G HIGH to Output in High-Z	t _{HZOE}	t _{dis(G)}		15	ns	
ELOW to Output in Low-Z	t _{LZCE}	t _{en(E)}	3		ns	
G LOW to Output in Low-Z	t _{LZOE}	t _{en(G)}	0		ns	
Output Hold Time from Address Change	t _{OH}	t _{v(A)}	3		ns	
ELOW to Power-Up Time	t _{PU}		0		ns	
E HIGH to Power-Down Time	t _{PD}			70	ns	

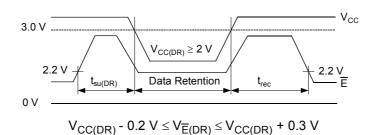
Switching Characteristics	Syr	nbol	7	Unit	
Write Cycle	Alt.	IEC	Min.	Max.	Unit
Write Cycle Time	t _{WC}	t _{cW}	70		ns
Write Pulse Width	t _{WP}	t _{w(W)}	35		ns
Write Setup Time	t _{WP}	t _{su(W)}	35		ns
Address Setup Time	t _{AS}	t _{su(A)}	0		ns
Address Valid to End of Write	t _{AW}	t _{su(A-WH)}	40		ns
Chip Enable Setup Time	t _{CW}	t _{su(E)}	40		ns
Pulse Width Chip Enable to End of Write	t _{CW}	t _{w(E)}	40		ns
Data Setup Time	t _{DS}	t _{su(D)}	25		ns
Data Hold Time	t _{DH}	t _{h(D)}	0		ns
Address Hold from End of Write	t _{AH}	t _{h(A)}	0		ns
WLOW to Output in High-Z	t _{HZWE}	t _{dis(W)}		20	ns
G HIGH to Output in High-Z	t _{HZOE}	t _{dis(G)}		15	ns
WHIGH to Output in Low-Z	t _{LZWE}	t _{en(W)}	0		ns
G LOW to Output in Low-Z	t _{LZOE}	t _{en(G)}	0		ns

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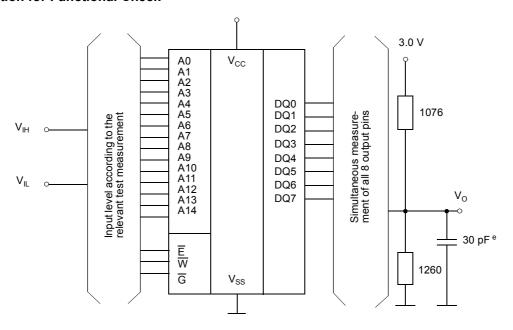
Data Retention Mode

E - controlled



Data Retention	Symbol		Conditions		_		11!4
Characteristics	Alt.	IEC	Conditions	Min.	Тур.	Max.	Unit
Data Retention Supply Voltage		V _{CC(DR)}		2			٧
Data Retention Supply Current		I _{CC(DR)}	$V_{CC(DR)} = 2V$ $V_{\overline{E}} = V_{CC(DR)} - 0.2 V$			5 20	μΑ μΑ
Data Retention Setup Time	t _{CDR}	t _{su(DR)}	See Data Retention	0			ns
Operating Recovery Time	t _R	t _{rec}	Waveforms (above)	t _{cR}			ns

Test Configuration for Functional Check



 $^{^{\}rm e}$ In measurement of $t_{\rm dis(E)}$, $t_{\rm dis(W)}$, $t_{\rm en(E)}$, $t_{\rm en(W)}$, $t_{\rm en(G)}$ the capacitance is 5 pF.



Capacitance	Conditions	Symbol	Min.	Max.	Unit
Input Capacitance	$V_{CC} = 3.3V$ $V_{I} = V_{SS}$	Cı		7	pF
Output Capacitance	$t = 1 \text{ MHz}$ $T_a = 25 \text{ °C}$	Co		7	pF

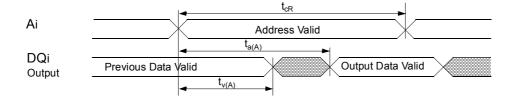
All pins not under test must be connected with ground by capacitors.

Alliance	Organization	VCC Range	Package	Operating Temp	Speed ns
AS62V256A-70SIN	32K x 8	2.7V – 3.6V	SOP28 (330 mil)	Industrial ~ -40°C - 85°C	70

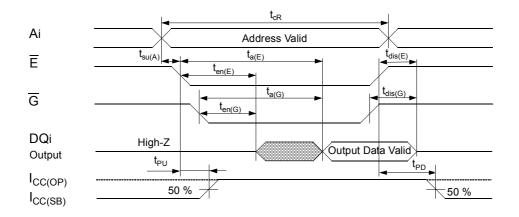


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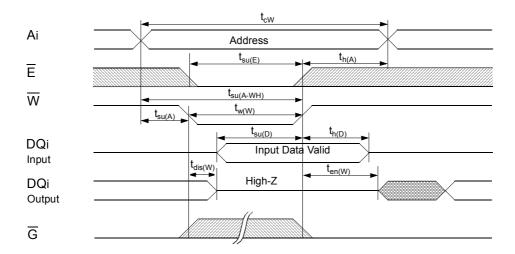
Read Cycle 1: A_i -controlled (during Read Cycle : $\overline{E} = \overline{G} = V_{IL}$, $\overline{W} = V_{IH}$)



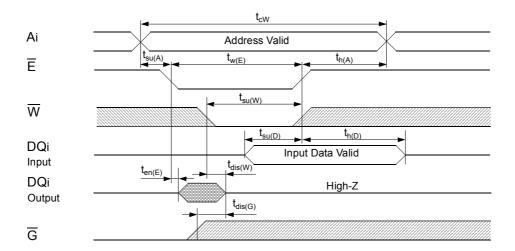
Read Cycle 2: \overline{G} -, \overline{E} -controlled (during Read Cycle: $\overline{W} = V_{IH}$)



Write Cycle1: W-controlled



Write Cycle 2: E-controlled





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